

LA/OC Chapter Ballot Meeting Topic Survey Results for 11/20/2009

General:	Votes
Industry Trends	17
Cleaning	11
Failure Analysis	11
Lean Manufacturing	11
Soldering Processes	11
Advanced Packaging: BGA, CSP, 0201	10
Lead-Free / RoHS / WEEE / REACH	10
Test, AOI, X-ray	10
DFM	9
Flex/Rigid Flex	8
Quality	8
Standards	7
Six Sigma	6
PCB Surface Finishes	5
Alternative Energy	4
Material Control	4
Printing/Dispensing Challenges	4
Chip on Board	3
Environmental Issues / Halogen Free	2
Other	2
Other Responses	
Reliability	1
Conformal Coat	1
Surface Mount Components	1